

03-18-2002

Docket No.: SEC.927

FORM 10-1595 (Modified)
(Rev. 03-01)
OMB No. 0651-0027 (exp 5/31/2002)
POBA/REV03



HEET

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

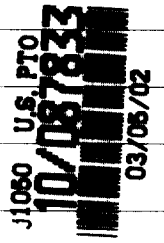
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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies): AHN, Gye-Tak
3/5/02
Additional names(s) of conveying party(ies) Yes No

2. Name and address of receiving party(ies):
Name: SAMSUNG ELECTRONICS CO., LTD.
Address: 416, Maetan-dong, Paldal-gu,
City: Suwon-city, Kyungki-do State/Prov.:
Country: Republic of Korea ZIP:
Additional name(s) & address(es) Yes No



3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other
Execution Date: February 27, 2002

4. Application number(s) or patent numbers(s):
If this document is being filed together with a new application, the execution date of the application is: Feb. 27, 2002
Patent Application No. NEW Filing date MARCH 5, 2002
03/11/2002 HDEMESS1 00000010 10087833
01 FC:581 40.00 OP
Additional numbers Yes No

B. Patent No.(s) 10/08 7833
 Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: ADAM C. VOLENTINE
Registration No. 33289
Address: VOLENTINE FRANCOS, PLLC
12200 SUNRISE VALLEY DRIVE, SUITE 150
City: RESTON State/Prov.: VA
Country: U.S.A. ZIP: 20191

6. Total number of applications and patents involved: 1
7. Total fee (37 CFR 3.41):.....\$ 40.00
 Enclosed - Any excess or insufficiency should be credited or debited to deposit account
 Authorized to be charged to deposit account
8. Deposit account number:
50-0238
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9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.
ADAM C. VOLENTINE *[Signature]* MARCH 4, 2002
Name of Person Signing Signature 3 Date

Total number of pages including cover sheet, attachments, and
Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments

PATENT
REEL: 012671 FRAME: 0233

ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to

each of the undersigned

Insert Name(s) of Inventor(s) AHN, Gye-Tak

the undersigned hereby sell(s) and assign(s) to

Insert Name(s) of Assignee(s) SAMSUNG ELECTRONICS CO., LTD.
of 416, Maetan-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea

Address (hereinafter designated as the Assignee) the entire right, title and interest for the United States as defined in 35 USC 100, in the invention known as

WAFER SUPPORT PLATE ASSEMBLY HAVING RECESSED UPPER PAD AND VACUUM PROCESSING APPARATUS COMPRISING THE SAME

Title of Invention for which an application for patent in the United States of America has been executed by the undersigned on FEB 27, 2002

Date of Signing of Application The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) to Adam C. Volentine, Reg. No. 33,289 and William S. Francos, Reg. No. 38,456, and the firm of VOLENTINE FRANCO, P.L.L.C. the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date FEB. 27. 2002, Name of Inventor AHN GYE-TAK
Date _____, Name of Inventor Gye-Tak AHN
Date _____, Name of Inventor _____
Date _____, Name of Inventor _____
Date _____, Name of Inventor _____

(Note regarding Witnessing and/or Acknowledgment: Acknowledgment before a United States Consul is preferred but not required. If not acknowledged, then it is recommended that the execution by the Inventor(s) be witnessed by at least two witnesses who sign here. However, the current practice of the U.S. Patent and Trademark Office is to record an Assignment even if it has not been acknowledged and/or witnessed.)

Witness
Witness

ACKNOWLEDGMENT

} ss

This _____ day of _____, 19____, before me personally came the above-named _____ to me personally known as the individual(s) who executed the foregoing assignment, who did acknowledge to me that he (they) executed the same of his (their) own free will for the purposes therein set forth.

Official Signature

SEAL

Official Title

Applicant Reference No.: AW-6033-US/DH Atty Docket No.: SEC.927
Serial No.: _____ Filing Date: _____